## SKiiP 37NAB066V1



MiniSKiiP®3

3-phase bridge rectifier + brake chopper + 3-phase bridge inverter SKiiP 37NAB066V1

**Target Data** 

### **Features**

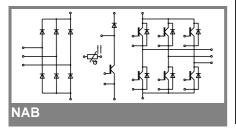
- Trench IGBT
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

## **Typical Applications**

- Inverter up to 18 kVA
- Typical motor power 7,5 kW

#### Remarks

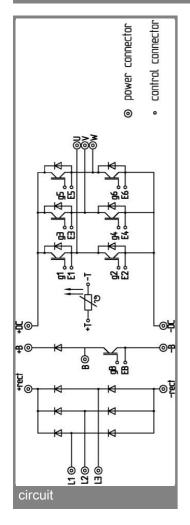
- Case temperature limited to T<sub>C</sub> =
- · Product reliability results are valid for  $T_i = 150$ °C
- SC data:  $t_p \le 6 \mu s$ ;  $V_{GE} \le 15 V$ ;  $T_j = 150 ^{\circ} C$ ,  $V_{CC} = 360 V$   $V_{CEsat}$ ,  $V_F = chip level value$

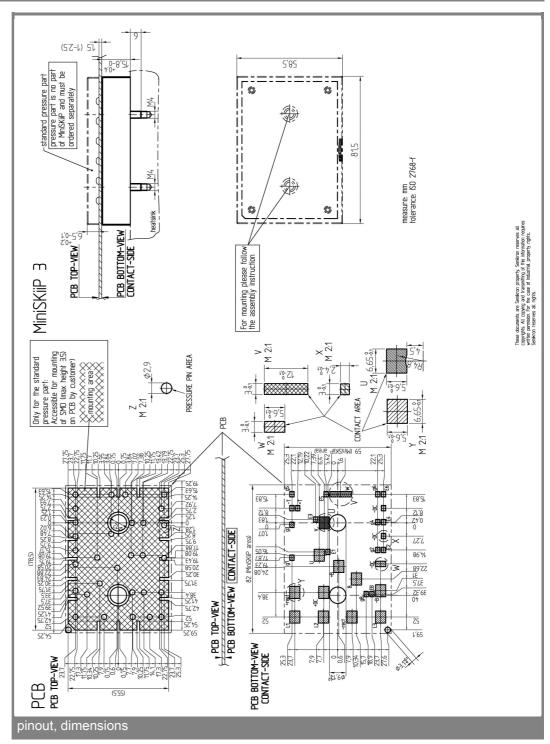


Absolute	Maximum Ratings	S = 25 °C, unless otherwise specified					
Symbol	Conditions	Values	Units				
IGBT - Inverter							
$V_{CES}$		600	V				
I <sub>C</sub>	$T_s = 25 (70)  ^{\circ}C, T_j = 150  ^{\circ}C$	79 (53)	Α				
I <sub>C</sub>	$T_s = 25 (70)  ^{\circ}C, T_j = 175  ^{\circ}C$	88 (65)	Α				
I <sub>CRM</sub>	$t_p = 1 \text{ ms}$	150	Α				
$V_{GES}$		± 20	V				
Diode - Inverter							
I <sub>F</sub>	$T_s = 25 (70)  ^{\circ}C, T_i = 150  ^{\circ}C$	65 (42)	Α				
I <sub>F</sub>	$T_s = 25 (70)  ^{\circ}\text{C},  T_j = 175  ^{\circ}\text{C}$	77 (56)	Α				
I <sub>FRM</sub>	t <sub>p</sub> = 1 ms	150	Α				
Diode - Rectifier							
$V_{RRM}$		800	V				
I <sub>F</sub>	T <sub>s</sub> = 70 °C	61	Α				
I <sub>FSM</sub>	$t_p = 10 \text{ ms, sin } 180 ^{\circ}, T_j = 25 ^{\circ}\text{C}$	700	Α				
i²t	$t_p = 10 \text{ ms, sin } 180 ^{\circ},  T_j = 25 ^{\circ}\text{C}$	2400	A²s				
I <sub>tRMS</sub>	per power terminal (20 A / spring)	80	Α				
T <sub>i</sub>	IGBT, Diode	-40+175	°C				
T <sub>stg</sub>		-40+125	°C				
V <sub>isol</sub>	AC, 1 min.	2500	V				

Characteristics T <sub>S</sub> = 25 °C, unless otherwise sp					ecified			
Symbol	Conditions	min.	typ.	max.	Units			
IGBT - Inverter								
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 75 A, T <sub>i</sub> = 25 (150) °C	1,05	1,45 (1,65)	1,85 (2,05)	V			
V <sub>GE(th)</sub>	$V_{GE} = V_{CE}$ , $I_C = 1 \text{ mA}$		5,8		V			
V <sub>CE(TO)</sub>	T <sub>j</sub> = 25 (150) °C		0,85 (0,7)	1,1 (1)	V			
r <sub>CE</sub>	T <sub>j</sub> = 25 (150) °C		8 (12,7)	10 (14)	mΩ			
C <sub>ies</sub>	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		4,4		nF _			
C <sub>oes</sub>	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		0,78		nF			
C <sub>res</sub>	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		0,66		nF			
R <sub>CC'+EE'</sub>	spring contact-chip T <sub>s</sub> = 25 (150 )°C				mΩ			
$R_{th(j-s)}$	per IGBT		0,75		K/W			
t <sub>d(on)</sub>	under following conditions		115		ns			
t <sub>r</sub>	$V_{CC} = 300 \text{ V}, V_{GE} = -8\text{V}/+15\text{V}$		45		ns			
t <sub>d(off)</sub>	$I_{Cnom} = 75 \text{ A}, T_j = 150 \text{ °C}$		475		ns			
t <sub>f</sub>	$R_{Gon} = R_{Goff} = 8.2 \Omega$		60		ns			
$E_{on} \left( E_{off} \right)$	inductive load		2,7 (3)		mJ			
Diode - Inverter								
$V_F = V_{EC}$	I <sub>F</sub> = 75 A, T <sub>i</sub> = 25 (150) °C		1,5 (1,5)	1,7 (1,7)	V			
$V_{(TO)}$	T <sub>i</sub> = 25 (150) °C		1 (0,9)	1,1 (1)	V			
r <sub>T</sub>	T <sub>j</sub> = 25 (150) °C		6,7 (8)	8 (9,3)	mΩ			
$R_{th(j-s)}$	per diode		1,2		K/W			
I <sub>RRM</sub>	under following conditions		52		Α			
$Q_{rr}$	I <sub>Fnom</sub> = 75 A, V <sub>R</sub> = 300 V		8		μC			
E <sub>rr</sub>	V <sub>GE</sub> = 0 V, T <sub>i</sub> = 150°C		1,8		mJ			
	di <sub>F</sub> /dt = 1480 A/μs							
Diode - Rectifier								
$V_{F}$	I <sub>Fnom</sub> = 35 A, T <sub>i</sub> = 25 °C		1,1		V			
V <sub>(TO)</sub>	T <sub>i</sub> = 150 °C		0,8		V			
r <sub>T</sub>	T <sub>j</sub> = 150 °C		11		mΩ			
$R_{th(j-s)}$	per diode		0,9		K/W			
Temperature Sensor								
R <sub>ts</sub>	3 %, T <sub>r</sub> = 25 (100) °C		1000(1670)		Ω			
Mechanical Data								
w			97		g			
M <sub>s</sub>	Mounting torque	2		2,5	Nm			

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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.